ABSTRACT OF THE DISCLOSURE

SUBSTRATE FOR SEMICONDUCTOR DEVICE, SEMICONDUCTOR CHIP MOUNTING SUBSTRATE, SEMICONDUCTOR DEVICE AND METHOD OF FABRICATION THEREOF, AND CIRCUIT BOARD, TOGETHER WITH ELECTRONIC EQUIPMENT

A substrate for semiconductor device which is formed of a material that can be cut into separate pieces and has mounting regions for a plurality of semiconductor chips, and at least one hole is formed therein at a position of intersection between a plurality of cutting lines for cutting the substrate into a plurality of individual products.

FIG. 1